

Figure 1 Dimensions	DFN1006-2 / DFN1006H4-2	MiniMELF	MELF	SOD-323	SOD-123	SOD-523	SMA	SMB	SMC
Z	1.1	4.8	6.3	3.75	4.9	2.3	6.5	6.7	9.3
G	0.3	2.1	3.3	1.05	2.5	1.1	1.5	1.8	4.4
X	0.7	1.7	2.7	0.65	0.7	0.8	1.7	2.3	3.3
Y	0.4	1.3	1.5	1.35	1.2	0.6	2.5	2.5	2.5
C	0.7	3.5	4.8	2.40	3.7	1.7	4.0	4.3	6.8

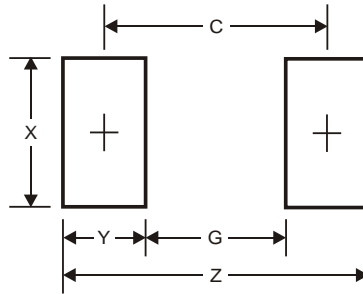


Fig. 1

Figure 2 Dimensions	DFN1006-3 / DFN1006H4-3
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

Figure 3 Dimensions	DFN1411-3
Z	1.38
G1	0.15
G2	0.15
X	0.95
X1	0.75
X2	0.40
Y	0.75
C	0.76

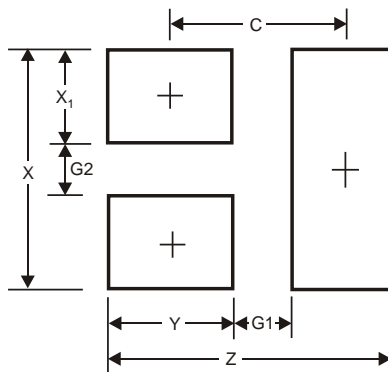


Fig. 2

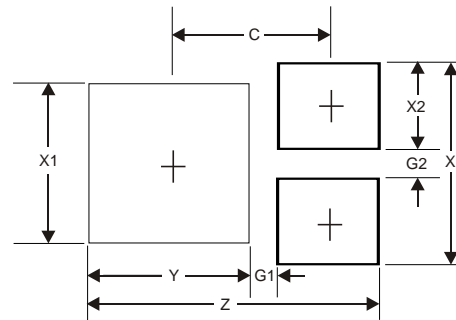


Fig. 3

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

Figure 4 Dimensions	DFN1612-6	DFN1310H4-6
G1	0.15	0.16
G2	0.175	0.17
G3	0.15	0.15
X1	0.60	0.52
X2	0.25	0.20
Y1	0.65	0.52
Y2	0.45	0.375
a	0.10	0.09
b	0.15	0.06

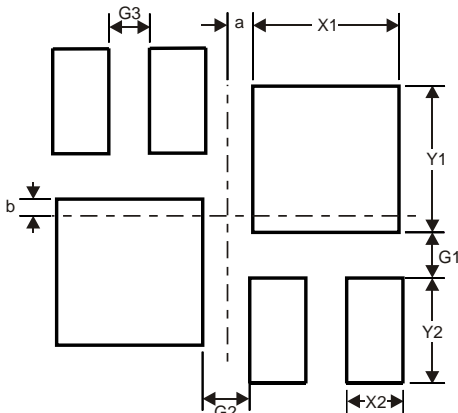


Fig. 4

Figure 5 Dimensions	DFN1616-6
Z	1.3
G	0.175
X1	0.50
X2	0.525
Y	0.30
C	0.50

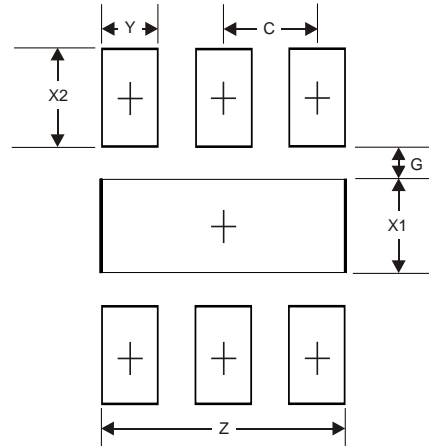


Fig. 5

Figure 6 Dimensions	DFN1616-8
G1	0.15
G2	0.20
X1	0.65
X2	0.25
Y1	1.25
Y2	0.50
C	0.40
a	0.10

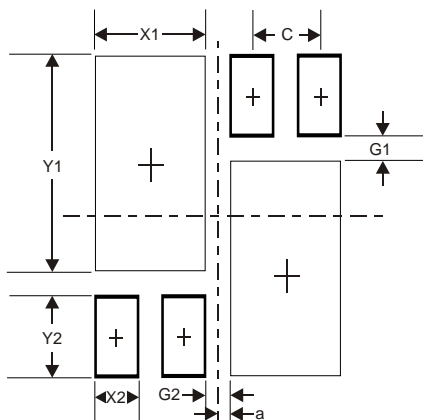


Fig. 6

Figure 7 Dimensions	DFN2020-3
Z	0.45
Z1	1.722
X	0.35
Y	1.00
Y1	0.40
C	1.00

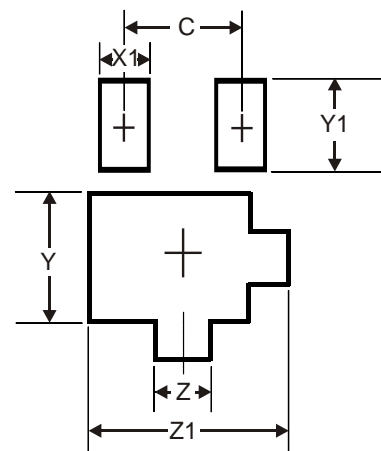


Fig. 7

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Figure 8 Dimensions	DFN2020-6
Z	1.67
G	0.15
X1	0.90
X2	0.45
Y	0.37
C	0.65

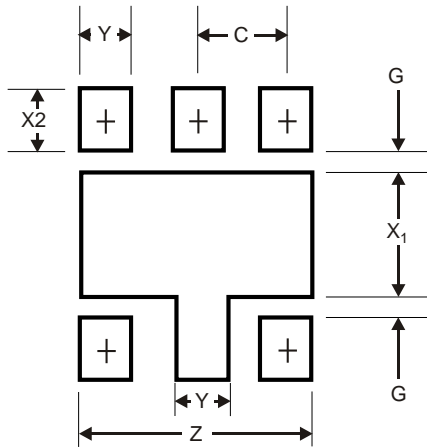


Fig. 8

Figure 9 Dimensions	DFN2020B-6
Z	1.67
G	0.20
G1	0.40
X1	1.0
X2	0.45
Y	0.37
Y1	0.70
C	0.65

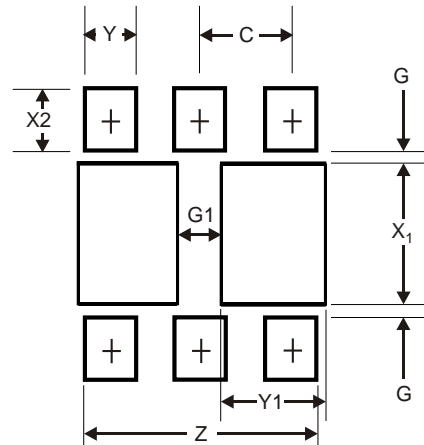


Fig. 9

Figure 10 Dimensions	DFN3030-8
Z	2.59
G	0.11
X1	2.49
X2	0.65
Y	0.39
C	0.65

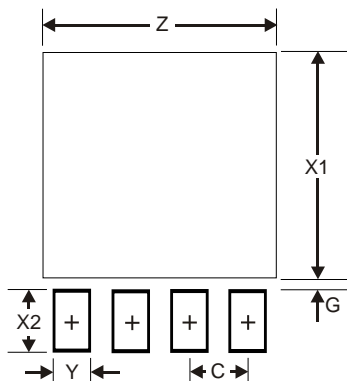


Fig. 10

Figure 11 Dimensions	DFN3030-10
Z	3.00
G	0.15
X	3.00
X1	0.60
Y	0.30
C	0.50

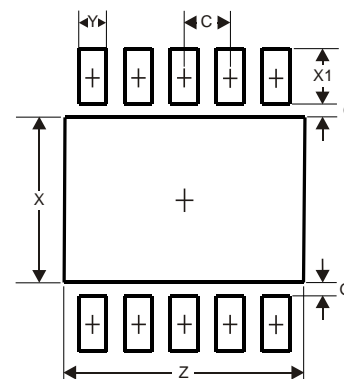


Fig. 11

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

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Figure 12 Dimensions	DFN3030-12
Z	3.00
G	0.15
X	3.00
X1	0.60
Y	0.30
C	0.50

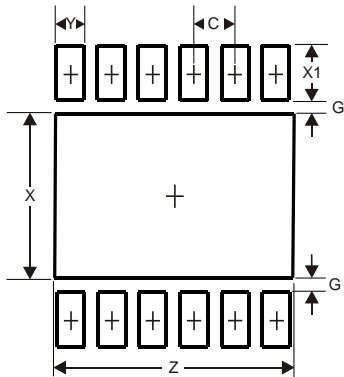


Fig. 12

Figure 13 Dimensions	DF-S	MiniDIP
Z	10.26	6.91
X	1.2	0.60
Y	1.52	0.76
C	5.2	2.67

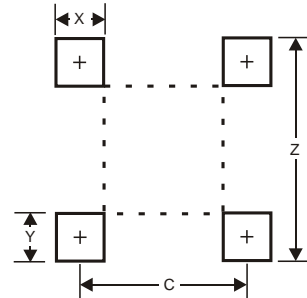


Fig. 13

Figure 14 Dimensions	DPAK	D ² PAK
Z	11.6	16.9
X1	1.5	1.1
X2	7.0	10.8
Y1	2.5	3.5
Y2	7.0	11.4
C	6.9	9.5
E1	2.3	2.5

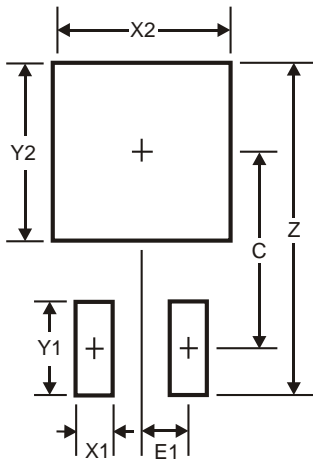


Fig. 14

Figure 15 Dimensions	MSOP-10L
X	0.20
Y	0.8
C1	4.2
C2	0.50

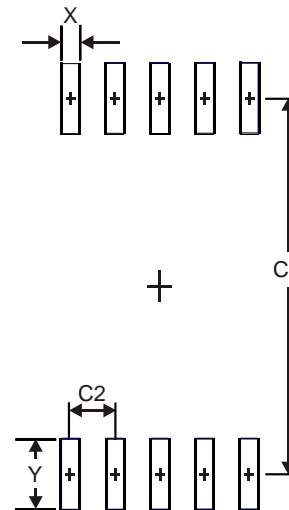


Fig. 15

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Figure 16 Dimensions	MSOP-8L
X	0.32
Y	0.8
C1	4.2
C2	0.65

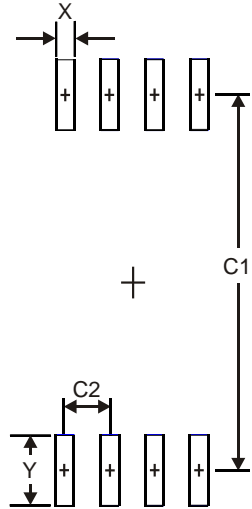


Fig. 16

Figure 17 Dimensions	PowerDI 123	PowerDI 323
G	1.0	0.5
X1	2.2	2.0
X2	0.9	0.8
Y1	1.4	0.8
Y2	1.4	1.1

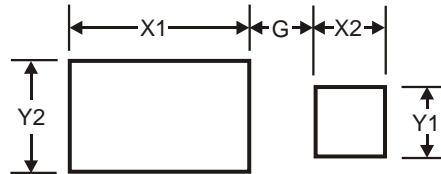


Fig. 17

Figure 18 Dimensions	PowerDI 5
Z	6.6
X1	1.4
X2	3.6
Y1	0.8
Y2	4.7
C	3.87
E1	0.9

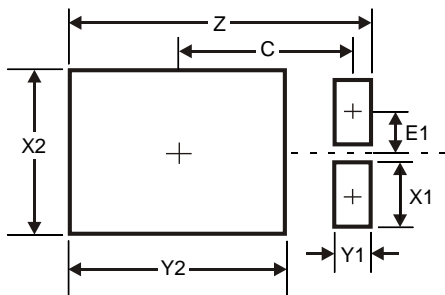


Fig. 18

Figure 19 Dimensions	SOP-14L
X	0.60
Y	1.50
C1	5.4
C2	1.27

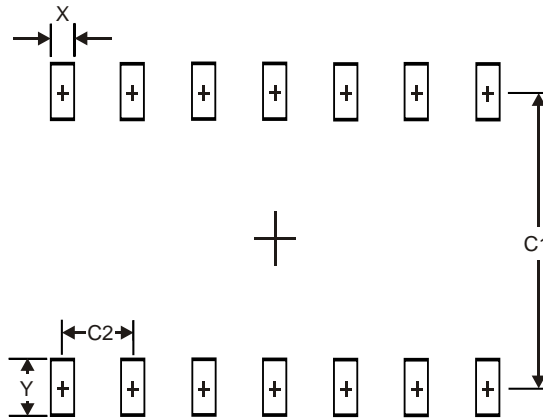


Fig. 19

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PowerDI is a registered trademark of Diodes Incorporated.

Figure 20 Dimensions	SOP-16L
X	0.60
Y	1.50
C1	5.4
C2	1.27

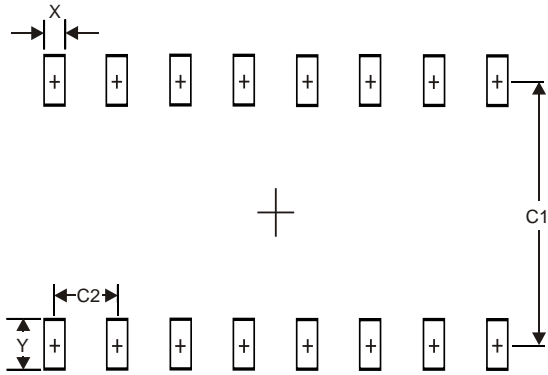


Fig. 20

Figure 21 Dimensions	SOP-8L
X	0.60
Y	1.55
C1	5.4
C2	1.27

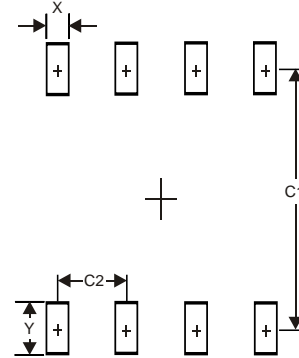


Fig. 21

Figure 22 Dimensions	SOT-143
Z	2.70
G	1.30
X	2.50
X1	1.0
X2	0.60
Y	0.70
C	2.0

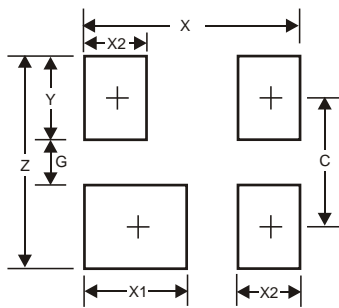


Fig. 22

Figure 23 Dimensions	SOT-223
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

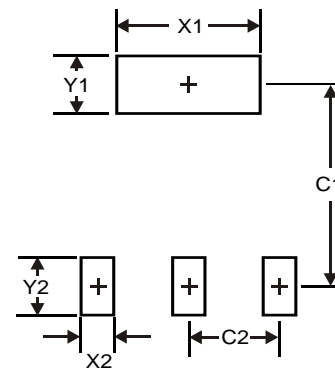


Fig. 23

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Figure 24 Dimensions	SOT-523	SOT-323	SOT-23	SC-59
Z	1.8	2.8	2.9	3.4
X	0.4	0.7	0.8	0.8
Y	0.51	0.9	0.9	1.0
C	1.3	1.9	2.0	2.4
E	0.7	1.0	1.35	1.35

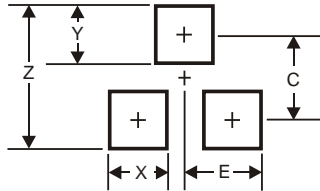
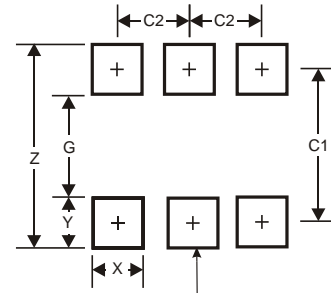


Fig. 24

Figure 25 Dimensions	SOT-363 / SOT-353	SOT-26 / SC-74R / SOT-25	SOT-563
Z	2.5	3.20	2.2
G	1.3	1.60	1.2
X	0.42	0.55	0.375
Y	0.6	0.80	0.5
C1	1.9	2.40	1.7
C2	0.65	0.95	0.5



Omit this pad for SOT-353 and SOT-25

Fig. 25

Figure 26 Dimensions	SOT89-3L
X1	1.7
X2	0.9
X3	0.4
Y1	2.7
Y2	1.3
Y3	1.9
C	3.0

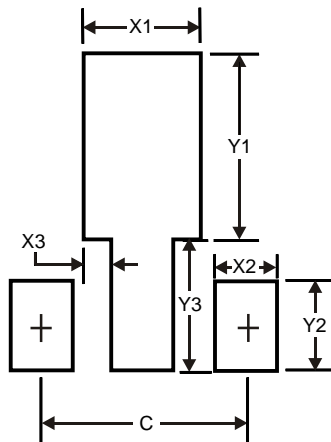


Fig. 26

Figure 27 Dimensions	SOT89-5L
X1	1.7
X2	0.55
X3	0.4
Y1	4.6
Y2	1.2
Y3	0.5
Y4	1.1
C	3.0

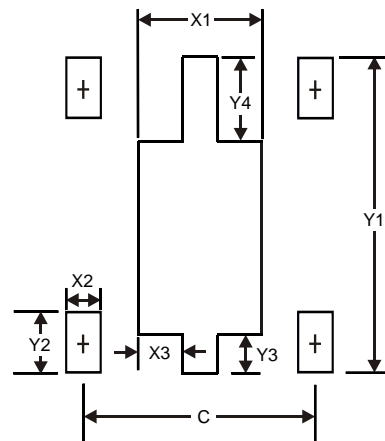


Fig. 27

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Figure 28 Dimensions	TO252-3L / DPAK	TO263-3L / D ² PAK
Z	11.6	16.9
X1	1.5	1.1
X2	7.0	10.8
Y1	2.5	3.5
Y2	7.0	11.4
C	6.9	9.5
E1	2.3	2.5

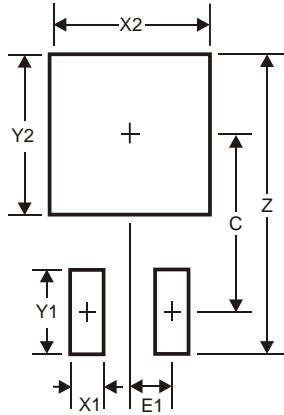


Fig. 28

Figure 29 Dimensions	TO252-5L
X	5.6
X1	0.6
Y	11.0
Y1	5.6
Y2	2.0
C1	7.2
C2	1.27

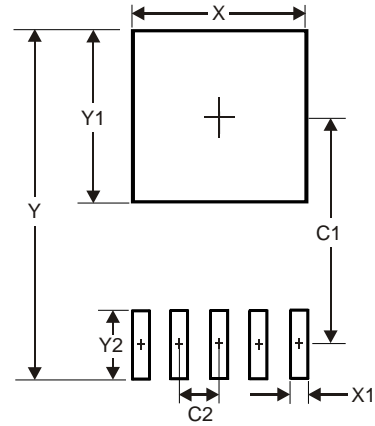


Fig. 29

Figure 30 Dimensions	TO263-5L
X	10.9
X1	1.05
Y	15.7
Y1	9.1
Y2	2.5
C	1.7

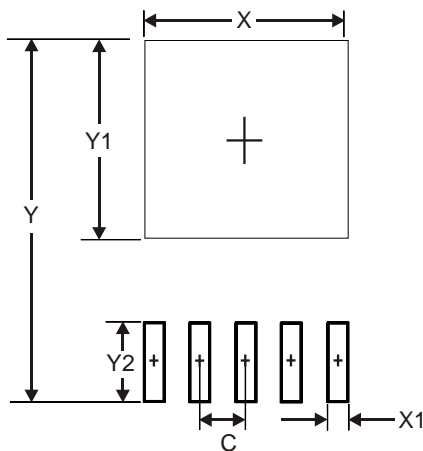


Fig. 30

Figure 31 Dimensions	TSSOP-14L
X	0.45
Y	1.45
C1	5.9
C2	0.65

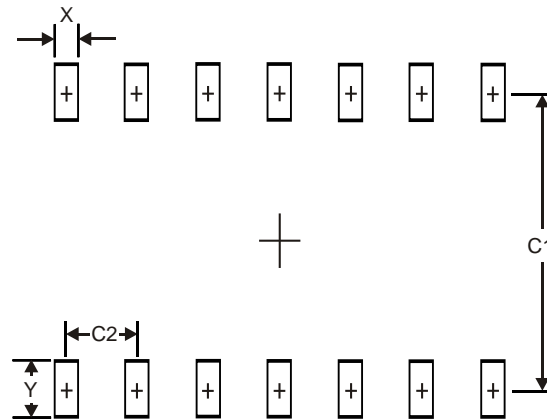


Fig. 31

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